

# IC Packaging Services Market, Global Outlook and Forecast 2022-2028

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## Abstracts

This report contains market size and forecasts of IC Packaging Services in Global, including the following market information:

Global IC Packaging Services Market Revenue, 2017-2022, 2023-2028, (\$ millions)

Global top five companies in 2021 (%)

The global IC Packaging Services market was valued at million in 2021 and is projected to reach US\$ million by 2028, at a CAGR of % during the forecast period.

The U.S. Market is Estimated at \$ Million in 2021, While China is Forecast to Reach \$ Million by 2028.

Traditional Packaging Segment to Reach \$ Million by 2028, with a % CAGR in next six years.

The global key manufacturers of IC Packaging Services include ASE, Amkor Technology, JCET, SPIL, Powertech Technology Inc., TongFu Microelectronics, Tianshui Huatian Technology, UTAC and Chipbond Technology, etc. In 2021, the global top five players have a share approximately % in terms of revenue.

MARKET MONITOR GLOBAL, INC (MMG) has surveyed the IC Packaging Services companies, and industry experts on this industry, involving the revenue, demand, product type, recent developments and plans, industry trends, drivers, challenges, obstacles, and potential risks.

Total Market by Segment:

Global IC Packaging Services Market, by Type, 2017-2022, 2023-2028 (\$ millions)

Global IC Packaging Services Market Segment Percentages, by Type, 2021 (%)

Traditional Packaging

Advanced Packaging

Global IC Packaging Services Market, by Application, 2017-2022, 2023-2028 (\$ millions)

Global IC Packaging Services Market Segment Percentages, by Application, 2021 (%)

Automotive and Transportation

Consumer Electronics

Communication

Others

Global IC Packaging Services Market, By Region and Country, 2017-2022, 2023-2028 (\$ Millions)

Global IC Packaging Services Market Segment Percentages, By Region and Country, 2021 (%)

North America

US

Canada

Mexico

## Europe

Germany

France

U.K.

Italy

Russia

Nordic Countries

Benelux

Rest of Europe

## Asia

China

Japan

South Korea

Southeast Asia

India

Rest of Asia

## South America

Brazil

Argentina

Rest of South America

Middle East & Africa

Turkey

Israel

Saudi Arabia

UAE

Rest of Middle East & Africa

## Competitor Analysis

The report also provides analysis of leading market participants including:

Key companies IC Packaging Services revenues in global market, 2017-2022  
(estimated), (\$ millions)

Key companies IC Packaging Services revenues share in global market, 2021 (%)

Further, the report presents profiles of competitors in the market, key players include:

ASE

Amkor Technology

JCET

SPIL

Powertech Technology Inc.

TongFu Microelectronics

Tianshui Huatian Technology

UTAC

Chipbond Technology

Hana Micron

OSE

Walton Advanced Engineering

NEPES

Unisem

ChipMOS Technologies

Signetics

Carsem

KYEC

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